Declaration For U.S. Patent Application

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

In-Mold Foam Molding Apparatus and Method, and In-Mold Foam Molded Article

The specification of which is attached hereto unless the following is checked:

was filed on	as Un	ited States Application Number or PC	T International	Application
Number	and was amen	nded on		
(if applicable).				
I hereby state that I have reviewed ar any amendment referred to above.	nd understand the contents of th	e above-identified specification, including	the claim(s), as	amended by
I acknowledge the duty to disclose infe	ormation which is material to pa	tentability as defined in Title 37, Code of	Federal Regulat	ions, § 1.56.
I hereby claim foreign priority bene	fits under Title 35. United Sta	ites Code, § 119 (a) – (d) of any foreign	application(s) for	or patent or
• • • •		foreign application for patent or invento		-
date before that of the application on	-			0 0
			Priority Cla	aimed
H11(1999)-277440	Japan	29/09/99	—— 🛛 Yes	□ No
(Number)	(Country)	(Day/Month/Year Filed)	_	
H11(1999)-327512	Japan	17/11/99	—— 🛂 Yes	☐ No
(Number)	(Country)	(Day/Month/Year Filed)		
H11(1999)-327513	Japan	17/11/99	🔀 Yes	□ No
(Number)	(Country)	(Day/Month/Year Filed)	_	_
H11(1999)-337091	Japan	29/11/99	—— 🏻 Yes	□ No
(Number)	(Country)	(Day/Month/Year Filed)		
<u>, </u>	See attached list for additional pr	rior foreign applications.		
I hereby claim the benefit under Title	35, United States Code, § 119(e)	of any United States provisional applicat	ion(s) listed belo	w.
(Application Number)		(Filing Date)		
(Application Number)	(Filing Date)		
T. 1	m:1 or 11 : 10:	100 C II : 10: : 11: :: () I'		c .1

I hereby claim that the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application

(List Prior U.S. Applications)	(Application Serial Number)	(Filing Date)	(Status) (patented, pending, abandoned)
*	(Application Serial Number)	(Filing Date)	(Status) (patented, pending, abandoned)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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